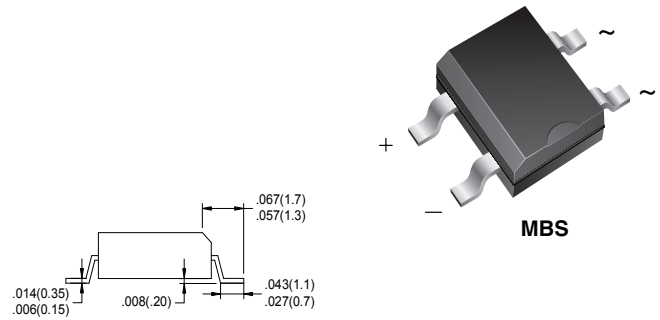
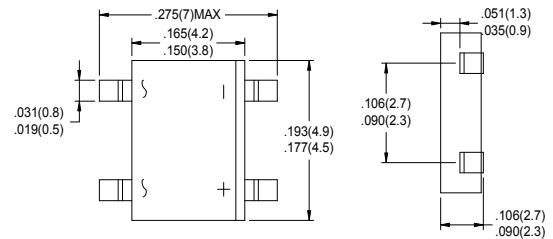


FEATURES

- UL Recognized Component
- High surge current capability
- Ideal for Printed Circuit Board
- Plastic Package - UL Flammability Classification 94V-0


MECHANICAL DATA

- Case: Transfer Molded Epoxy
- Mounting Position: Any
- Terminals: Plated leads solderable per MTL-STD-750, Method 2026



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%

| Characteristic | Symbol | MB 05S | MB 1S | MB 2S | MB 4S | MB 6S | MB 8S | MB 10S | Unit |
|---|------------------------------------|-------------|-------|-------|-------|-------|-------|--------|----------------------|
| Maximum Recurrent Peak Reverse Voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS Voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Average Rectified Output Current @ $T_A = 40^\circ\text{C}$ | $I_{F(AV)}$ | 0.8 | | | | | | | A |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | 30 | | | | | | | A |
| I^2t Rating for Fusing ($t < 8.3\text{ms}$) | I^2t | 5.0 | | | | | | | A^2s |
| Forward Voltage per element @ $I_F = 0.5\text{A}$ | V_{FM} | 1.0 | | | | | | | V |
| Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_A=25^\circ\text{C}$ @ $T_A=100^\circ\text{C}$ | I_{RM} | 5.0 500 | | | | | | | μA |
| Typical Junction Capacitance per leg (Note1) | C_j | 13 | | | | | | | pF |
| Typical Thermal Resistance per leg (Note 2) | $R_{\theta JA}$ $R_{\theta JL}$ | 70 20 | | | | | | | $^\circ\text{C/W}$ |
| Operating and Storage Temperature Range | T_j, T_{STG} | -55 to +150 | | | | | | | $^\circ\text{C}$ |

- Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts
2. On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20mm) mounted on 0.05 x 0.05" (1.3 x 1.3mm) solder pad

Typical Characteristics

